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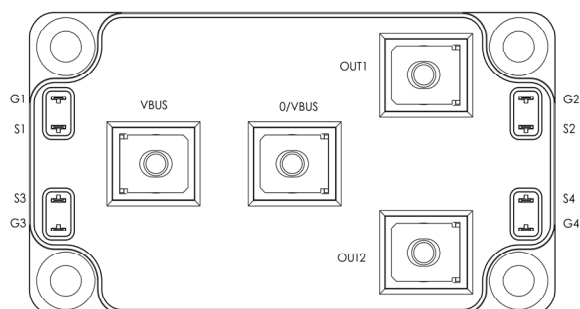
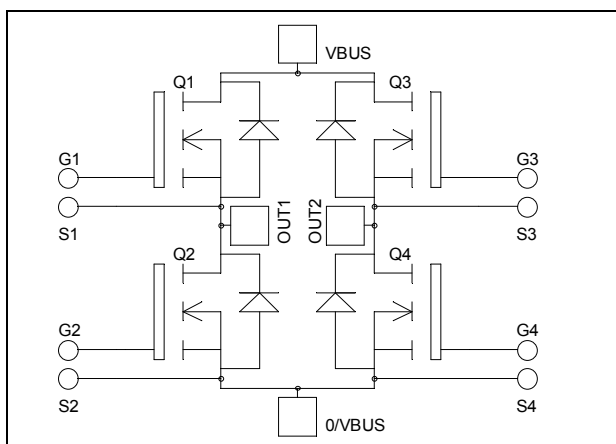


Full - Bridge MOSFET Power Module

$$V_{DSS} = 200V$$

$$R_{DSon} = 8m\Omega \text{ typ @ } T_j = 25^\circ C$$

$$I_D = 208A \text{ @ } T_c = 25^\circ C$$



Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Power MOS 7[®] FREDFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Fast intrinsic reverse diode
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	200	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$ 208 $T_c = 80^\circ C$ 155	A
I_{DM}	Pulsed Drain current	832	
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	10	m Ω
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$ 781	W
I_{AR}	Avalanche current (repetitive and non repetitive)	100	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	3000	



CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 200V$			375	μA
		$T_j = 25^\circ\text{C}$				
		$V_{GS} = 0V, V_{DS} = 160V$			1500	
		$T_j = 125^\circ\text{C}$				
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 104A$		8	10	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 5\text{mA}$	3		5	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			± 150	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$		14.4		nF
C_{oss}	Output Capacitance	$V_{DS} = 25V$		4.66		
C_{rss}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		0.29		
Q_g	Total gate Charge	$V_{GS} = 10V$		280		nC
Q_{gs}	Gate – Source Charge	$V_{Bus} = 100V$		106		
Q_{gd}	Gate – Drain Charge	$I_D = 208A$		134		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 133V$ $I_D = 208A$ $R_G = 2.5\Omega$		32		ns
T_r	Rise Time			64		
$T_{d(off)}$	Turn-off Delay Time			88		
T_f	Fall Time			116		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 208A, R_G = 2.5\Omega$		1698		μJ
E_{off}	Turn-off Switching Energy			1858		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 208A, R_G = 2.5\Omega$		1872		μJ
E_{off}	Turn-off Switching Energy			1972		

Source - Drain diode ratings and characteristics

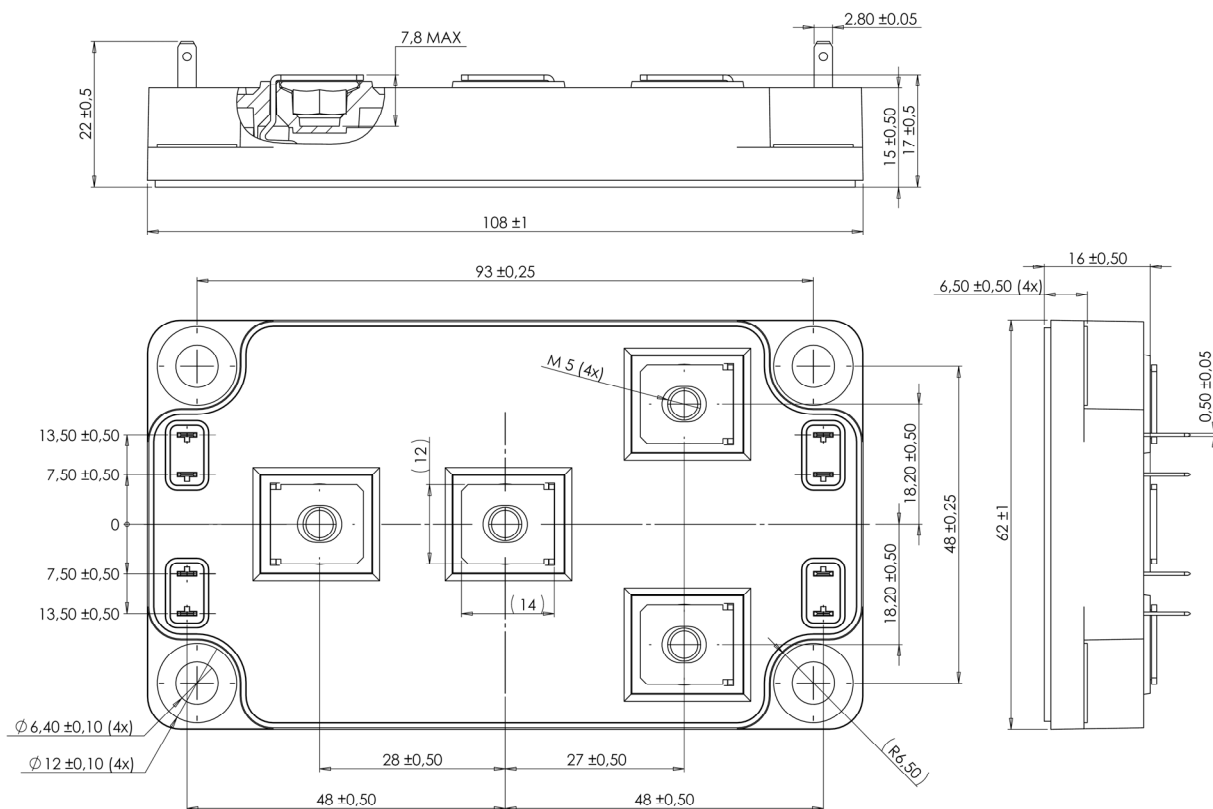
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I _S	Continuous Source current (Body diode)		T _C = 25°C			208	A
			T _C = 80°C			155	
V _{SD}	Diode Forward Voltage	V _{GS} = 0V, I _S = - 208A				1.3	V
dv/dt	Peak Diode Recovery ❶					5	V/ns
t _{rr}	Reverse Recovery Time	I _S = - 208A V _R = 133V di _S /dt = 200A/μs	T _j = 25°C			230	ns
			T _j = 125°C			450	
Q _{rr}	Reverse Recovery Charge		T _j = 25°C		1.8		μC
			T _j = 125°C		6.8		

❶ dv/dt numbers reflect the limitations of the circuit rather than the device itself.

$I_S \leq -208A$ $di/dt \leq 700A/\mu\text{s}$ $V_R \leq V_{DSS}$ $T_j \leq 150^\circ\text{C}$

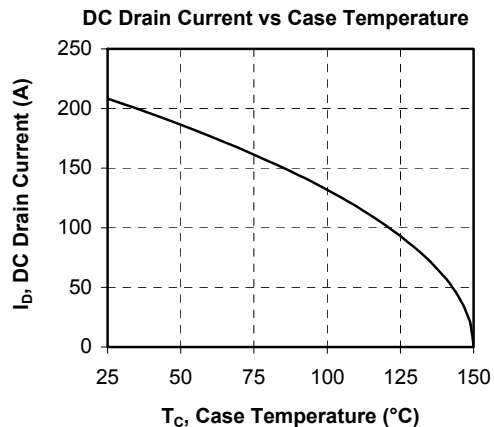
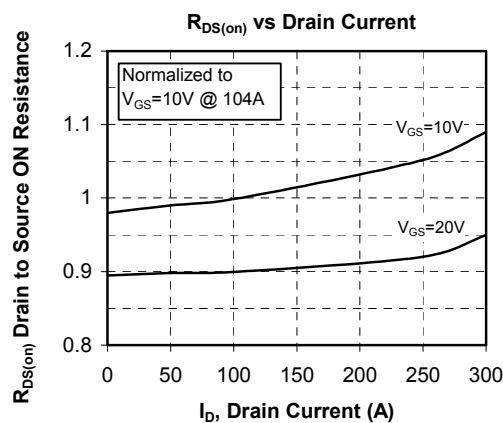
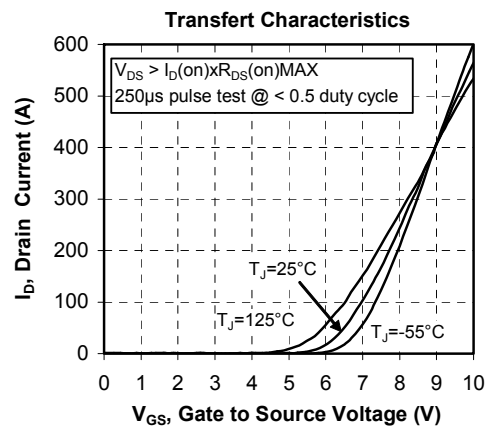
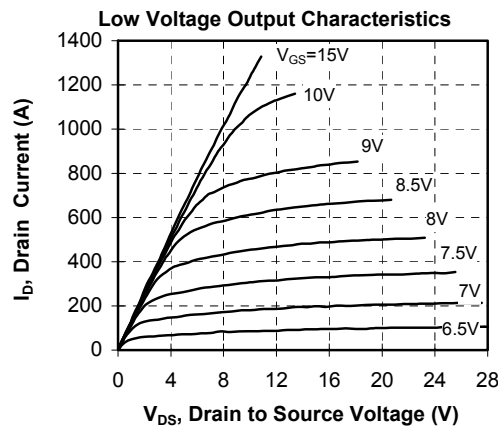
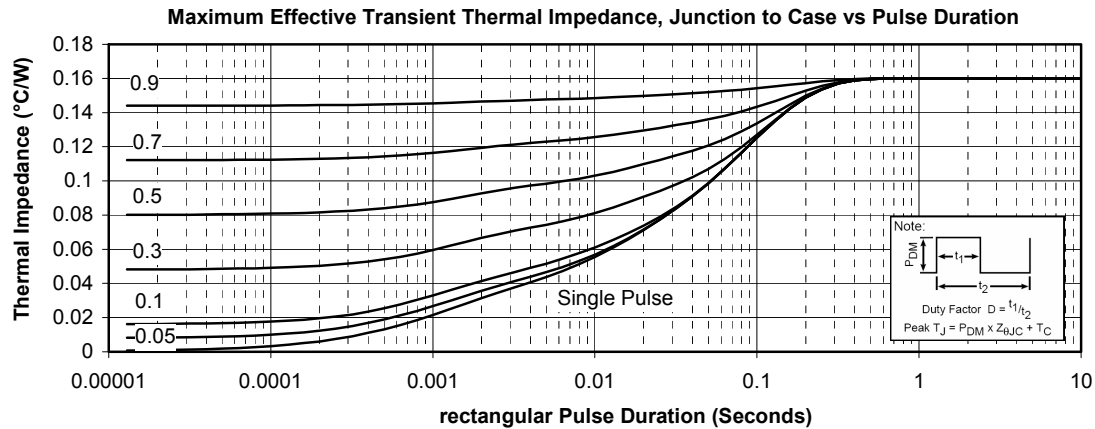
Thermal and package characteristics

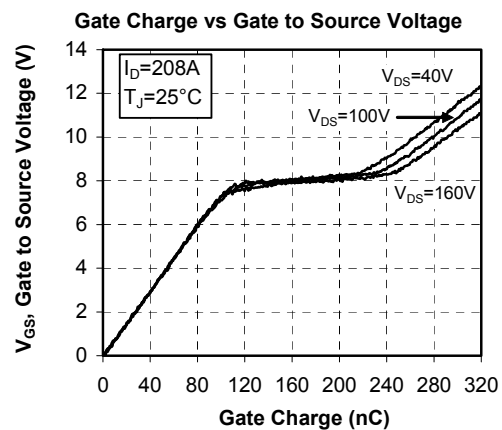
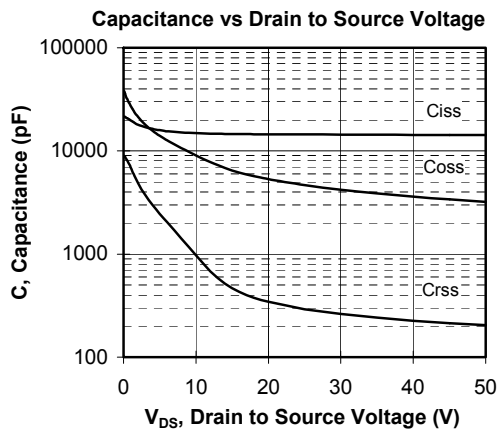
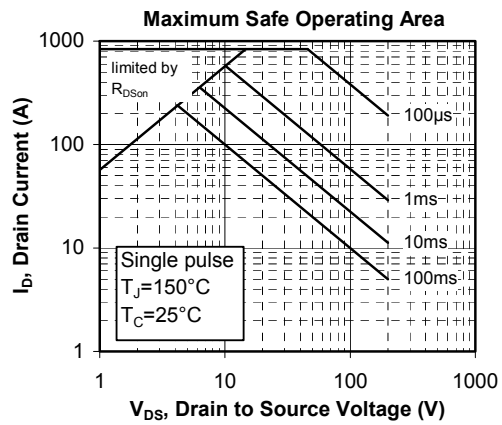
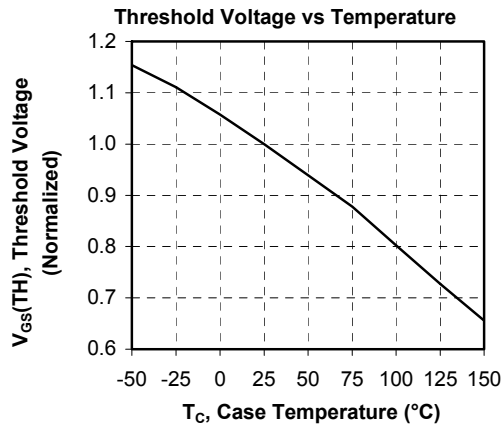
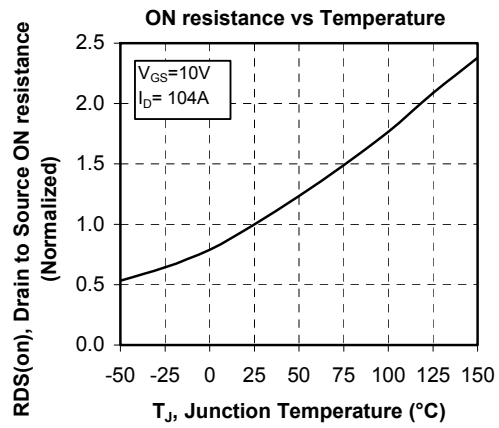
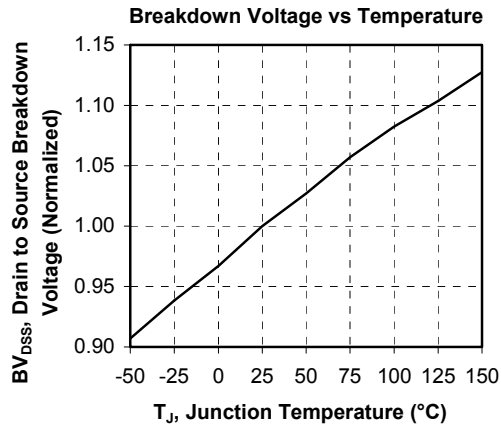
Symbol	Characteristic	Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance			0.16	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz	4000			V
T_J	Operating junction temperature range	-40		150	°C
T_{STG}	Storage Temperature Range	-40		125	
T_C	Operating Case Temperature	-40		100	
Torque	Mounting torque	To heatsink	M6	3	N.m
		For terminals	M5	2	
Wt	Package Weight			300	g

SP6 Package outline (dimensions in mm)


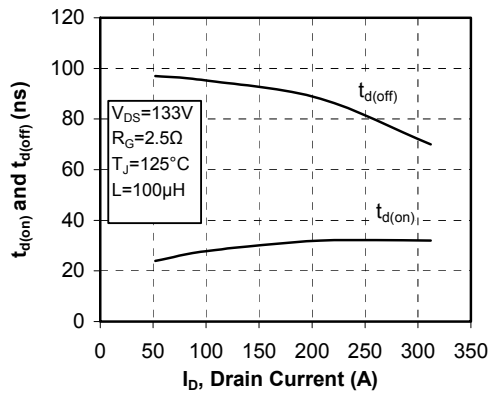
See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

Typical Performance Curve

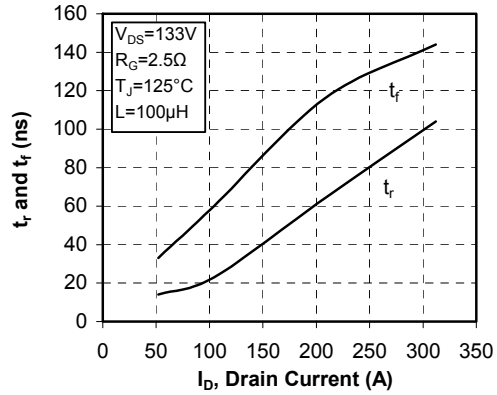




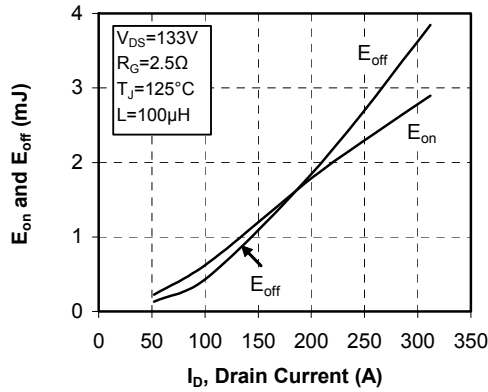
Delay Times vs Current



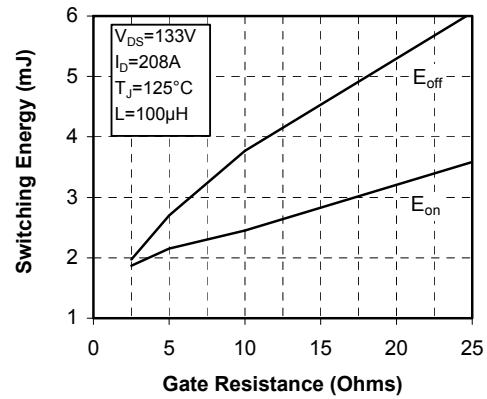
Rise and Fall times vs Current



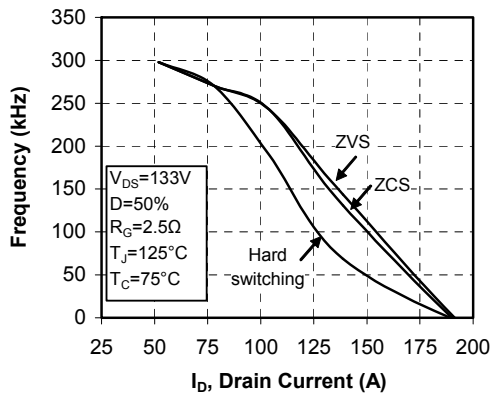
Switching Energy vs Current



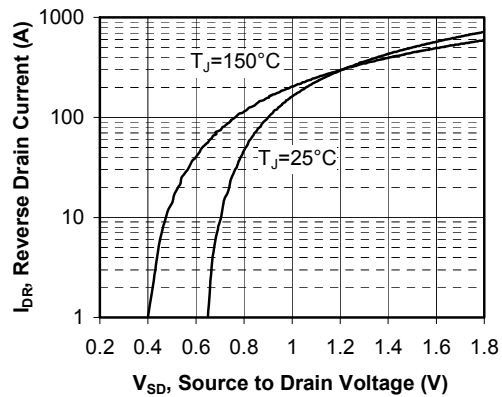
Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage



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